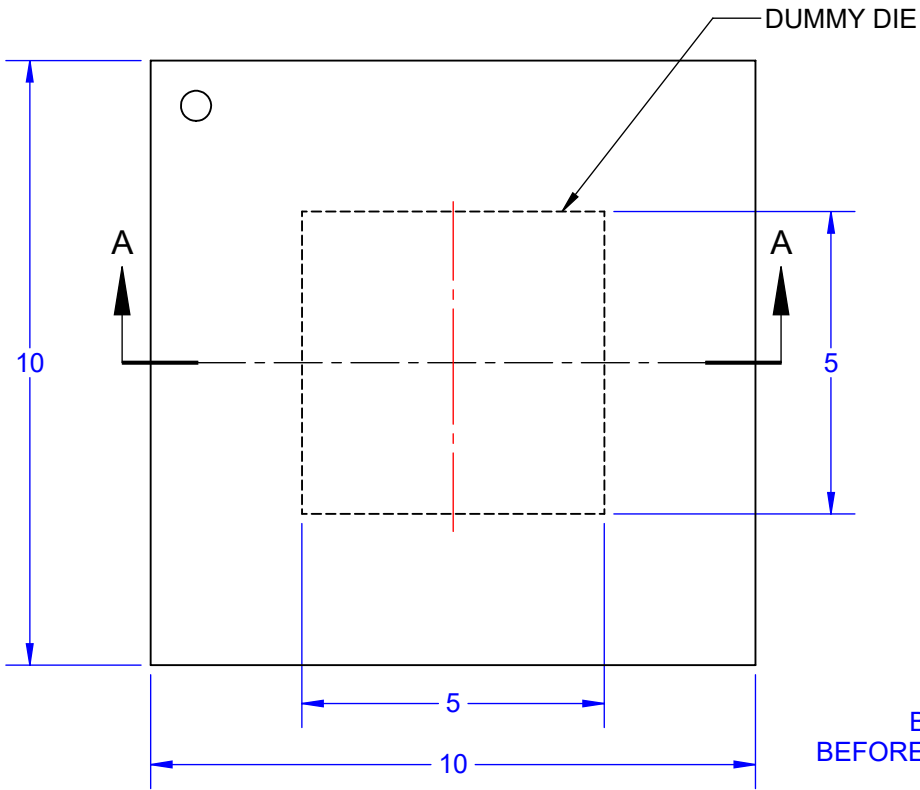
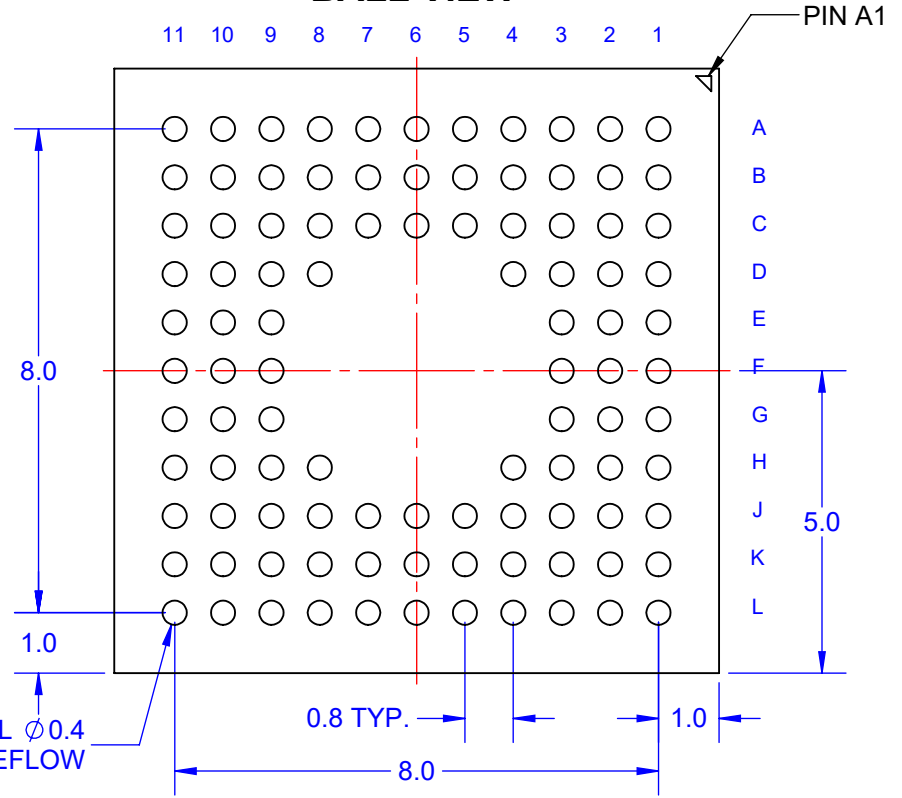


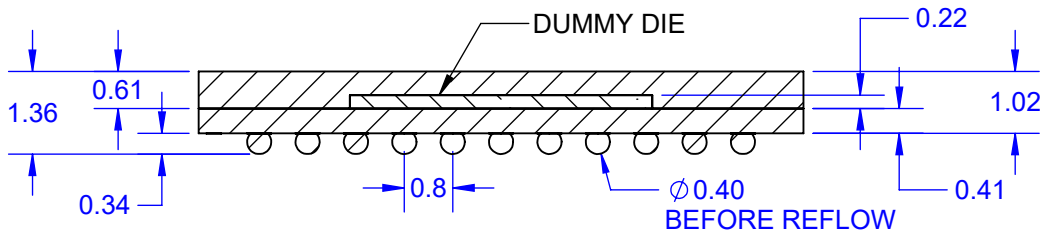
TOP VIEW



BALL VIEW



BALL $\phi 0.4$
BEFORE REFLOW




SECTION A-A
SCALE 8 : 1

Notes: (Unless Otherwise Specified).

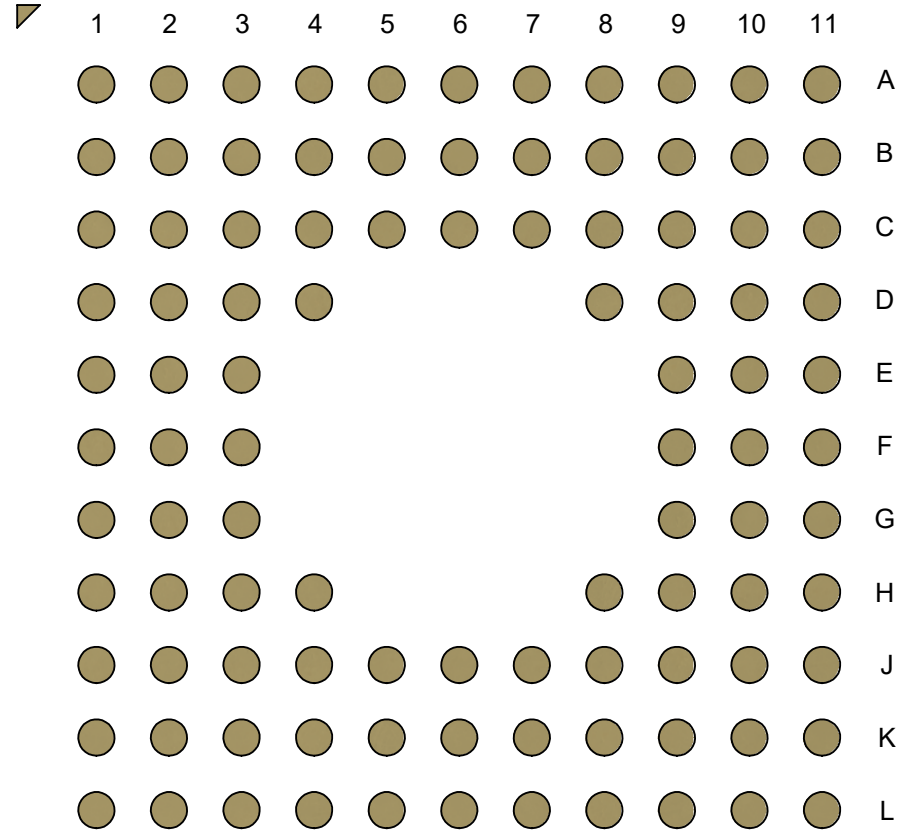
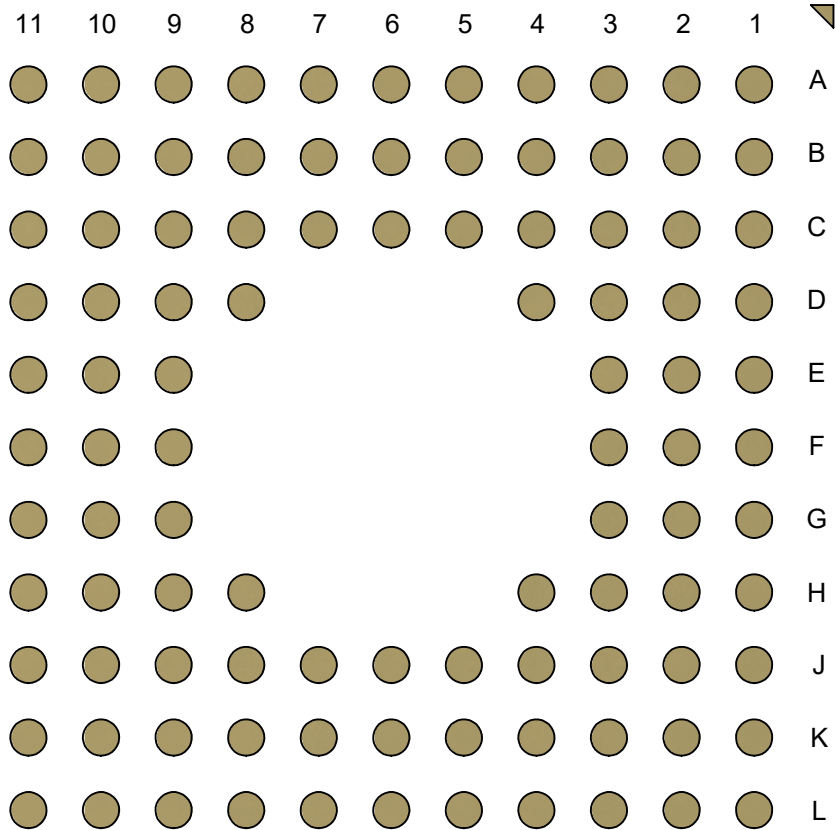
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.37mm (14.5 MIL).
- 5) PAD Cu DIAMETER: 0.406mm (16 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE: SIZE OPTIONAL.
- 8) PAD PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA100T.8C-11x11-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA100T.8-11x11-D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T. Au	7/17/2021				
ENG M. Hart	7/17/2021	TITLE BGA100T.8-11x11-D DUMMY BGA			
MFG		SCALE 15:1	SIZE A	DRAWING NO. 160725	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 3
CUST					
REVISED					

BALL VIEW

BOTTOM VIEW (TOP X-RAY VIEW)



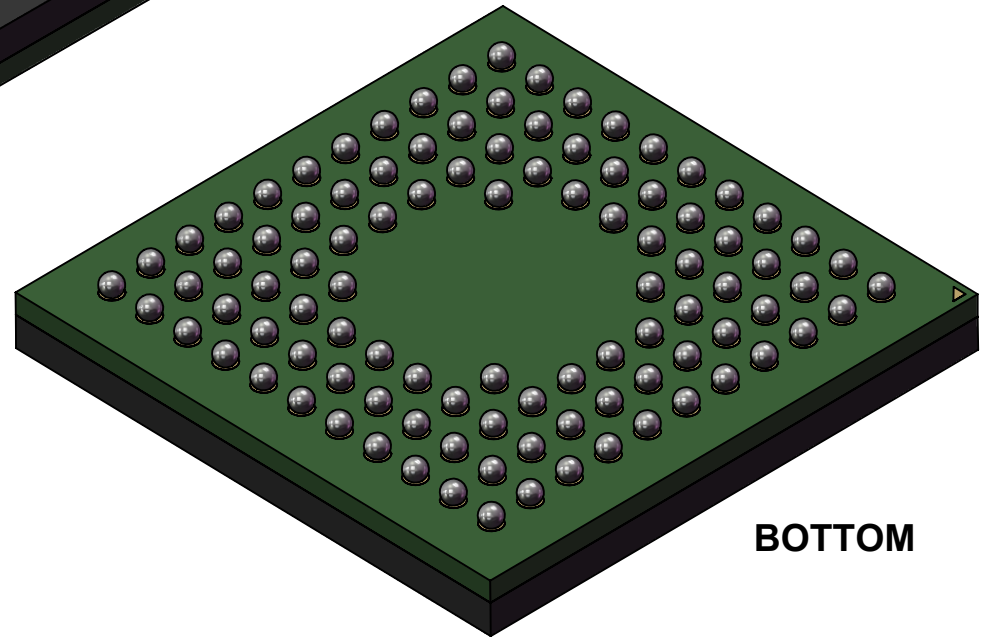
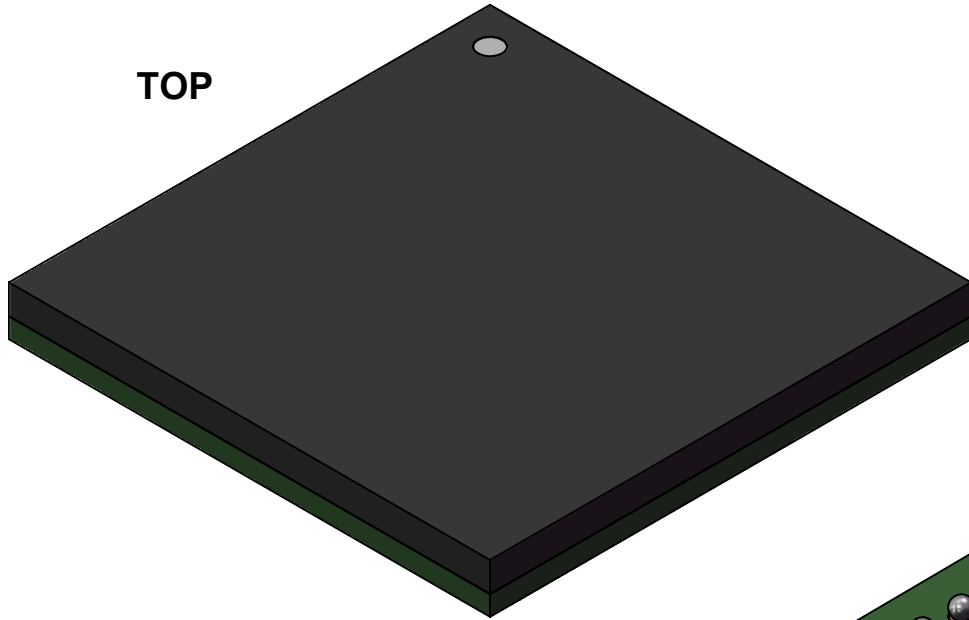
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.406mm (16 MIL).
- 3) PCB TRACING LINE WIDTH 1.52mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.37mm (14.5 MIL).

TopLine®			
TITLE		BGA100T.8-11x11-D DUMMY BGA	
SCALE	SIZE	DRAWING NO.	REV
12:1	A	160725	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BOTTOM

TopLine[®]

TITLE BGA100T.8-11x11-D
DUMMY BGA

SCALE 9:1	SIZE A	DRAWING NO. 160725	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3